Driving decarbonization and digitalization. Together.



Senior Director Process Integration and Product Engineering

Job description

In your new role you will:

- Lead a team of managers and top experts for the Wide Band Gap (WBG) technologies in the frontend wafer fab, covering Process Integration (PI), Product Engineering (PE), Substrate and Defect Density Engineering (SDE) functions.
- Establish a Product Matrix (PMX) organization with diverse sub-technologies in SiC and GaN as per different applications and business requirements.
- Establish a sub-team structure to support the PMX activities with Technology Data Innovations, Change Management, Harmonization and Synchronization with reference sites.
- Build the diverse WBG team by hiring, training, developing, and retaining talents for the current and future needs of the business. Build team's and individual competencies by identifying development needs and defining suitable development measures.
- Lead Technology and Product transfers from reference/mother fabs and qualify technologies as per business division requirements.
- Lead Technology and Product ramp-up and support the volume and capacity ramp in collaboration with planning and manufacturing by matching and releasing new tools.
- Improve overall technology and product yield and stability by optimizing processes, inline and electrical parameters, substrate and defect density in the substrate and Epi block.
- Drive overall WBG technologies and products high-volume manufacturing strategy to achieve best-in-class performance regarding cost, quality, reliability, and delivery.
- Drive for Synchronization and Harmonization with Infineon's other wafer fabs manufacturing same technologies and products.
- Guide the teams for managing deviations/excursion management and ensure all material with the prove-to-ship approach.
- Interact and communicate effectively with Business divisions, technology development, process and product engineering, quality, and reliability engineering, and counterparts at the reference sites.
- Support innovation, technology, and product development activities in collaboration with R&D teams.
- Lead taskforces related to excursions, deviations, and urgent improvement topics.

At a glance

Location:

Job ID: **HRC0619752**

Start date: as soon as possible

Entry level: 5+ years

Type: Full time

Contract: Permanent

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Job ID: HRC0619752

www.infineon.com/jobs





 Function as an interface between Frontend wafer fab and Backend Assembly on yield/product engineering topics.

Profile

You are best equipped for this task if you have:

- Overall 15+ years of experience in semiconductor technology, thereof10+ years of management experience as a process integration or module/section head in high volume semiconductor manufacturing in the frontend wafer fab environment.
- Experience in high-volume manufacturing of Wide Band Gap (SiC and/or GaN) based technologies is highly desirable, however, candidates with experience in Si-based Power Semiconductor technologies will also be considered.
- Strong knowledge of Unit Processes, Process Integration, Device Physics and Process-Device interactions.
- Familiar with Technology and Product Transfers and Qualification methodologies
- Experience of ramping up technologies in high volume and New Products Introduction
- Good knowledge of technology requirements in terms of product application domain and corresponding quality/reliability expectations.
- Experienced with quality and reliability requirements of Automotive and Industrial products.
- Working knowledge of chip design/product development cycles, Wafer Fab Tools and Processes, High-volume Manufacturing Systems, Assembly and Packaging, Quality and Reliability requirements, and Failure Analysis
- Familiar with Change and Deviation management and problem-solving methodologies.
- Must be an initiative-taker who can work both independently and in groups.
- Able to lead, organize and coordinate multiple projects in a timely manner.
- Ability to collaborate with multiple teams and interfaces in a highly demanding, time-critical, and agile environment.

Benefits

Kulim: Coaching, mentoring networking possibilities; Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working conditions; Holiday child care; Medical coverage; On-site social counselling and works doctor; Health promotion programs; On-site gym, jogging paths, beachvolleyball, tennis & soccer court; On-site canteen; Private insurance offers; Flexible transition into retirement

Why Us

Driving decarbonization and digitalization. Together.

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness,



respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant's experience and skills.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

